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-	1	045245.apn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/02 14:16
-	2	6197181.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/02 14:19
-	2	6113771.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/02 14:19
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